

ABSTRACT OF THE DISCLOSURE

A novel visible light curable composition for forming a thermally conductive interface and a method of using the same is provided. The composition is used to promote the transfer of heat from a source of heat such as an electronic device to a heat dissipation device such as a heat sink. The composition includes an elastomeric base matrix containing a light curable catalyst, loaded with a thermally conductive filler material such as boron nitride grains or ceramic filler. After the compound is prepared, it is screen or stencil printed onto the desired surface and cured by exposure to visible light. The thermal interface is bonded to the desired surface and has sufficient compressibility to allow it to overcome the voids in the mating surface to which the assembly is mounted.